

FEATURES

Surface Mounting Design 8.3*8.3*6.0mm

- High Current Handling Capability 20000A @ 8/20 µs
- Low Capacitance and Insertion Loss
- Quick Response and Long Service Life
- Moisture sensitivity level: Level 1



8.3*8.3*6.0mm



APPLICATION INFORMATION

Communication equipment.

- Repeaters,Modems
- Telephone Interface,Line cards.

Data communication equipment.

AGENCY APPROVALS

lcon	Solderability		
RoHS	Compliance with 2011/65/EU		
HF	Compliance with IEC61249-2-21:2003		
P6	Mean lead free		
19.	UL Certificated E505857		

PRODUCT CHARACTERISTICS

Lead Material	Body Material Terminal Finish	
Copper or Fe-Ni alloy	Ceramics 100% Matte-Tin Plated	



ELECTRICAL PARAMETER

Parameter	Condition	Rating	Unit
DC Spark-over Voltage 1)	100V/s	800-1200	
Impulse Spark-over Voltage	At 1kV/μs	for 99 % of measured values ≤1700	V
impulse spark-over voltage	At 1kV/µs	Typical values of distribution ≤1650	
Discharge Current (8/20us) 2)	10 times	20	KA
AC Discharge Current	50Hz, 1S	20	А
Minimum Insulation Resistance	Test Voltage DC=250V	1	GΩ
Max. Capacitance 1MHz	V _{DC} =0.5V	1.5	
Operating and Storage Temperature		-40~125	°C

1) In ionized mode

2) Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

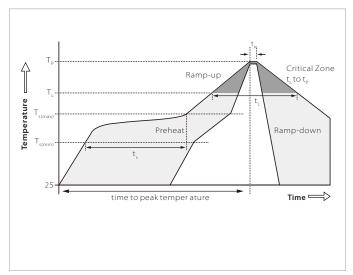
ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards	
High Temperature Storage Test	Temperature: 85°C ; Time:2H	
Low Temperature Storage Test	Temperature: -40°C ; Time:2H	
Vibration	Frequency: 10-500Hz ; Amplitude: 0.15mm ; Time:45min	
Resistance of soldering heat	Temperature: 260±5°C; Time of dip soldering: 10s, 1time	

NOTE: Up-screen program can be specified by customer's request via contacting Semiware service

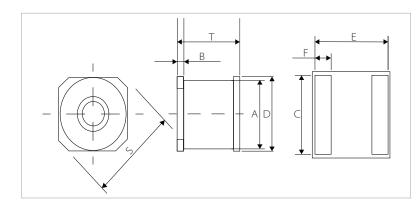
REFLOW PROFILE

Reflow Condition		Lead-free assembly	
	Temperature Min	150°C	
Pre Heat	Temperature Max	200°C	
	Time(min to max)	60-180 secs	
Average ra	amp up rate (Liquidus)Temp (T_L) to peak T _s (max)to T _L - Ramp-up Rate	3°C/second max	
Reflow	Temperature (T _{$l) (Liquidus)$}	217°C	
Reliow	Temperature (T _L)	60-150 seconds	
PeakTem	perature (T _p)	260+0/-5 °C	
Time within 5°C of actual peak Temperature (tp)		~10 seconds	
Ramp-down Rate		6°C/second max	
Time 25°C to peak Temperature (T _p)		8 minutes max.	
Do not exceed		260°C	





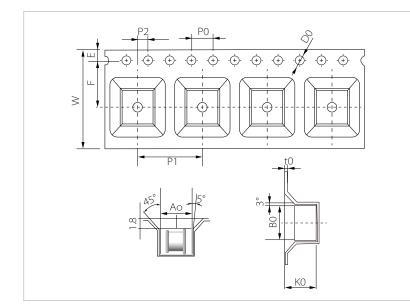
DIMENSIONS AND RECOMMENDED SOLDERING PAD



SEMIWARE®

Ref.	mm
A	8.0±0.2
В	0.5±0.1
С	9.0
D	8.3±0.2
E	6.7
F	1.2
Т	6.0±0.25
S	9.0±0.4

PACKAGE REEL INFORMATION



Ref.	mm
W	16.0±0.3
PO	4.0±0.1
P1	12.0±0.1
P2	2.0±0.1
DO	1.55±0.05
E	1.75±0.1
F	7.5±0.1
AO	6.35±0.1
КО	6.55±0.1
BO	8.65±0.1
tO	0.5±0.1

ORDERING INFORMATION

Part Number	Size	Marking	QTY/Reel	Reel Size
SG2R08B1000A	8.3*8.3*6.0mm	⊮ SG1000 <u>08</u>	600	13″



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